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Dated: December 22, 2004 Signature: \_\_\_\_\_

(Marcus J. Millet)

Docket No.: TESSERA 3.0-196 DIV  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Smith et al.

Application No.: 10/685,361

Filed: October 14, 2003

For: SEMICONDUCTOR CHIP PACKAGE WITH  
INTERCONNECT STRUCTURE

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: Group Art Unit: 2812  
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: Examiner: L. A. Gurley  
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:

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Official Action mailed June 22, 2004, applicant submits the following amendments and remarks.